

## Environmental Protection Agency

## § 433.11

Abrasive Jet Machining, Electric Discharge Machining, Electrochemical Machining, Electron Beam Machining, Laser Beam Machining, Plasma Arc Machining, Ultrasonic Machining, Sintering, Laminating, Hot Dip Coating, Sputtering, Vapor Plating, Thermal Infusion, Salt Bath Descaling, Solvent Degreasing, Paint Stripping, Painting, Electrostatic Painting, Electropainting, Vacuum Metalizing, Assembly, Calibration, Testing, and Mechanical Plating.

(b) In some cases effluent limitations and standards for the following industrial categories may be effective and applicable to wastewater discharges from the metal finishing operations listed above. In such cases these part 433 limits shall not apply and the following regulations shall apply:

Nonferrous metal smelting and refining (40 CFR part 421)  
Coil coating (40 CFR part 465)  
Porcelain enameling (40 CFR part 466)  
Battery manufacturing (40 CFR part 461)  
Iron and steel (40 CFR part 420)  
Metal casting foundries (40 CFR part 464)  
Aluminum forming (40 CFR part 467)  
Copper forming (40 CFR part 468)  
Plastic molding and forming (40 CFR part 463)  
Nonferrous forming (40 CFR part 471)  
Electrical and electronic components (40 CFR part 469)

(c) This part does not apply to:

(1) Metallic platemaking and gravure cylinder preparation conducted within or for printing and publishing facilities; and

(2) Existing indirect discharging job shops and independent printed circuit board manufacturers which are covered by 40 CFR part 413.)

[48 FR 32485, July 15, 1983; 48 FR 43682, Sept. 26, 1983; 48 FR 45105, Oct. 3, 1983; 51 FR 40421, Nov. 7, 1986]

### § 433.11 Specialized definitions.

The definitions set forth in 40 CFR part 401 and the chemical analysis methods set forth in 40 CFR part 136 are both incorporated here by reference. In addition, the following definitions apply to this part:

(a) The term “T”, as in “Cyanide, T”, shall mean total.

(b) The term “A”, as in “Cyanide A”, shall mean amenable to alkaline chlorination.

(c) The term “job shop” shall mean a facility which owns not more than 50% (annual area basis) of the materials undergoing metal finishing.

(d) The term “independent” printed circuit board manufacturer shall mean a facility which manufacturers printed circuit boards principally for sale to other companies.

(e) The term “TTO” shall mean total toxic organics, which is the summation of all quantifiable values greater than .01 milligrams per liter for the following toxic organics:

Acenaphthene  
Acrolein  
Acrylonitrile  
Benzene  
Benzidine  
Carbon tetrachloride (tetrachloromethane)  
Chlorobenzene  
1,2,4-Trichlorobenzene  
Hexachlorobenzene  
1,2-Dichloroethane  
1,1,1-Trichloroethane  
Hexachloroethane  
1,1-Dichloroethane  
1,1,2-Trichloroethane  
1,1,1,2-Tetrachloroethane  
Chloroethane  
Bis (2-chloroethyl) ether  
2-Chloroethyl vinyl ether (mixed)  
2-Chloronaphthalene  
2,4,6-Trichlorophenol  
Parachlorometa cresol  
Chloroform (trichloromethane)  
2-Chlorophenol  
1,2-Dichlorobenzene  
1,3-Dichlorobenzene  
1,4-Dichlorobenzene  
3,3-Dichlorobenzidine  
1,1-Dichloroethylene  
1,2-Trans-dichloroethylene  
2,4-Dichlorophenol  
1,2-Dichloropropane  
1,3-Dichloropropylene (1,3-dichloropropene)  
2,4-Dimethylphenol  
2,4-Dinitrotoluene  
2,6-Dinitrotoluene  
1,2-Diphenylhydrazine  
Ethylbenzene  
Fluoranthene  
4-Chlorophenyl phenyl ether  
4-Bromophenyl phenyl ether  
Bis (2-chloroisopropyl) ether  
Bis (2-chloroethoxy) methane  
Methylene chloride (dichloromethane)  
Methyl chloride (chloromethane)  
Methyl bromide (bromomethane)  
Bromoform (tribromomethane)  
Dichlorobromomethane  
Chlorodibromomethane  
Hexachlorobutadiene  
Hexachlorocyclopentadiene  
Isophorone

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Naphthalene  
Nitrobenzene  
2-Nitrophenol  
4-Nitrophenol  
2,4-Dinitrophenol  
4,6-Dinitro-o-cresol  
N-nitrosodimethylamine  
N-nitrosodiphenylamine  
N-nitrosodi-n-propylamine  
Pentachlorophenol  
Phenol  
Bis (2-ethylhexyl) phthalate  
Butyl benzyl phthalate  
Di-n-butyl phthalate  
Di-n-octyl phthalate  
Diethyl phthalate  
Dimethyl phthalate  
1,2-Benzanthracene  
(benzo(a)anthracene)  
Benzo(a)pyrene (3,4-benzopyrene)  
3,4-Benzofluoranthene (benzo(b)fluoranthene)  
1,12-Benzofluoranthene  
(benzo(k)fluoranthene)  
Chrysene  
Acenaphthylene  
Anthracene  
1,12-Benzoperylene (benzo(ghi)perylene)  
Fluorene  
Phenanthrene  
1,2,5,6-Dibenzanthracene  
(dibenzo(a,h)anthracene)  
Indeno(1,2,3-cd) pyrene (2,3-o-phenylene pyrene)  
Pyrene  
Tetrachloroethylene  
Toluene  
Trichloroethylene  
Vinyl chloride (chloroethylene)  
Aldrin  
Dieldrin  
Chlordane (technical mixture and metabolites)  
4,4-DDT  
4,4-DDE (p,p-DDX)  
4,4-DDD (p,p-TDE)  
Alpha-endosulfan  
Beta-endosulfan  
Endosulfan sulfate  
Endrin  
Endrin aldehyde  
Heptachlor  
Heptachlor epoxide  
(BHC-hexachloro-cyclohexane)  
Alpha-BHC  
Beta-BHC  
Gamma-BHC  
Delta-BHC  
(PCB-polychlorinated biphenyls)  
PCB-1242 (Arochlor 1242)  
PCB-1254 (Arochlor 1254)  
PCB-1221 (Arochlor 1221)  
PCB-1232 (Arochlor 1232)  
PCB-1248 (Arochlor 1248)  
PCB-1260 (Arochlor 1260)  
PCB-1016 (Arochlor 1016)  
Toxaphene

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2,3,7,8-Tetrachlorodibenzo-p-dioxin (TCDD)

[48 FR 32485, July 15, 1983; 48 FR 43682, Sept. 26, 1983, as amended at 51 FR 40421, Nov. 7, 1986]

**§ 433.12 Monitoring requirements.**

(a) In lieu of requiring monitoring for TTO, the permitting authority (or, in the case of indirect dischargers, the control authority) may allow dischargers to make the following certification statement: “Based on my inquiry of the person or persons directly responsible for managing compliance with the permit limitation [or pretreatment standard] for total toxic organics (TTO), I certify that, to the best of my knowledge and belief, no dumping of concentrated toxic organics into the wastewaters has occurred since filing of the last discharge monitoring report. I further certify that this facility is implementing the toxic organic management plan submitted to the permitting [or control] authority.” For direct dischargers, this statement is to be included as a “comment” on the Discharge Monitoring Report required by 40 CFR 122.44(i), formerly 40 CFR 122.62(i). For indirect dischargers, the statement is to be included as a comment to the periodic reports required by 40 CFR 403.12(e). If monitoring is necessary to measure compliance with the TTO standard, the industrial discharger need analyze for only those pollutants which would reasonably be expected to be present.

(b) In requesting the certification alternative, a discharger shall submit a solvent management plan that specifies to the satisfaction of the permitting authority (or, in the case of indirect dischargers, the control authority) the toxic organic compounds used; the method of disposal used instead of dumping, such as reclamation, contract hauling, or incineration; and procedures for ensuring that toxic organics do not routinely spill or leak into the wastewater. For direct dischargers, the permitting authority shall incorporate the plan as a provision of the permit.

(c) Self-monitoring for cyanide must be conducted after cyanide treatment and before dilution with other streams. Alternatively, samples may be taken of